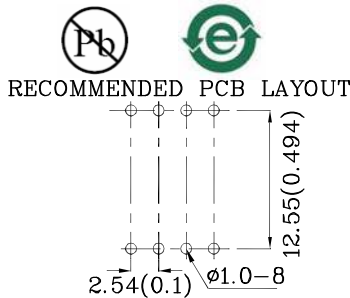
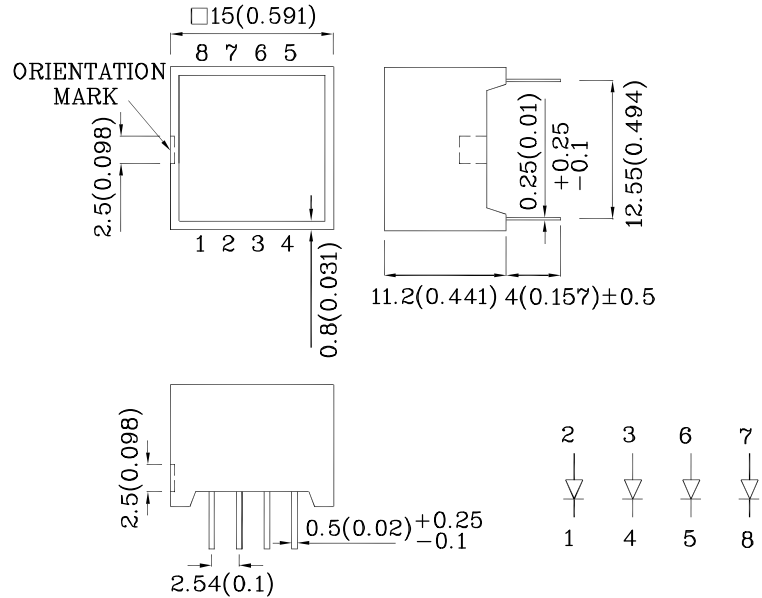


**Features**

- Robust package
- Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- RoHS compliant



**Package Schematics**



Notes:

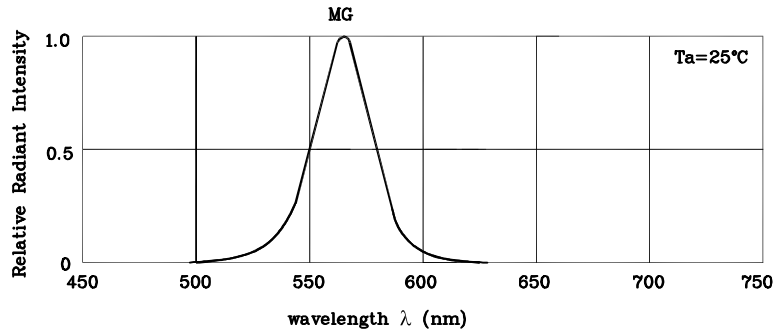
1. All dimensions are in millimeters (inches), Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
2. Specifications are subject to change without notice.

Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ )		MG (GaP)	Unit
Reverse Voltage	$V_R$	5	V
Forward Current	$I_F$	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{FS}$	140	mA
Power Dissipation	$P_D$	62.5	mW
Operating Temperature	$T_A$	-40 ~ +85	°C
Storage Temperature	$T_{stg}$	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds		

Operating Characteristics ( $T_A=25^\circ\text{C}$ )		MG (GaP)	Unit
Forward Voltage (Typ.) ( $I_F=20\text{mA}$ )	$V_F$	2.2	V
Forward Voltage (Max.) ( $I_F=20\text{mA}$ )	$V_F$	2.5	V
Reverse Current (Max.) ( $V_R=5\text{V}$ )	$I_R$	10	$\mu\text{A}$
Wavelength of Peak Emission CIE127-2007* (Typ.) ( $I_F=20\text{mA}$ )	$\lambda_P$	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) ( $I_F=20\text{mA}$ )	$\lambda_D$	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) ( $I_F=20\text{mA}$ )	$\Delta\lambda$	30	nm
Capacitance (Typ.) ( $V_F=0\text{V}$ , $f=1\text{MHz}$ )	C	15	pF

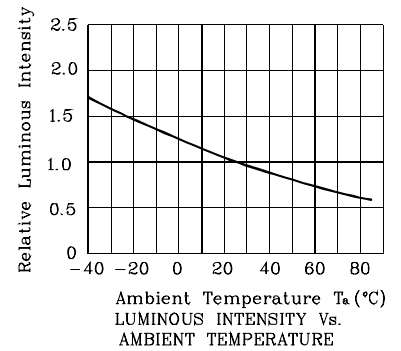
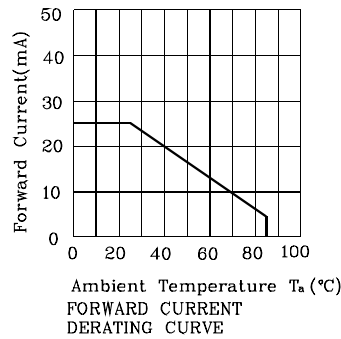
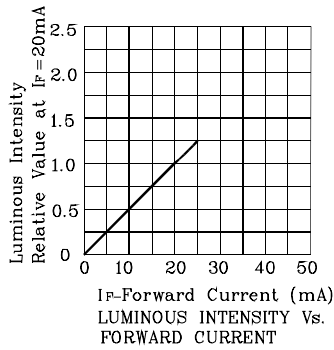
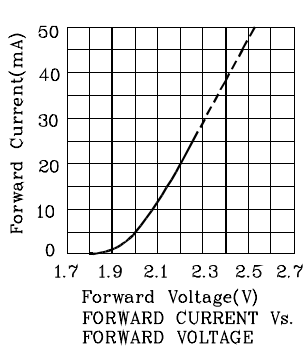
Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* ( $I_F=20\text{mA}$ ) mcd		Wavelength CIE127-2007* nm $\lambda_P$	Lens-color
			min.	typ.		
XEMG29DX	Green	GaP	40 8*	63 20*	565*	Green Diffused

\*Luminous intensity value and wavelength are in accordance with CIE127-2007

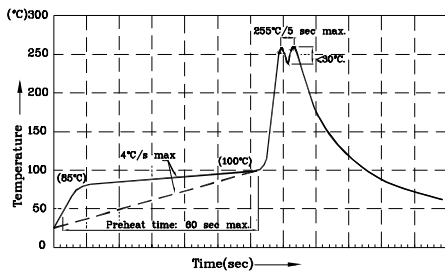


RELATIVE INTENSITY Vs. CIE WAVELENGTH

❖ MG



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.

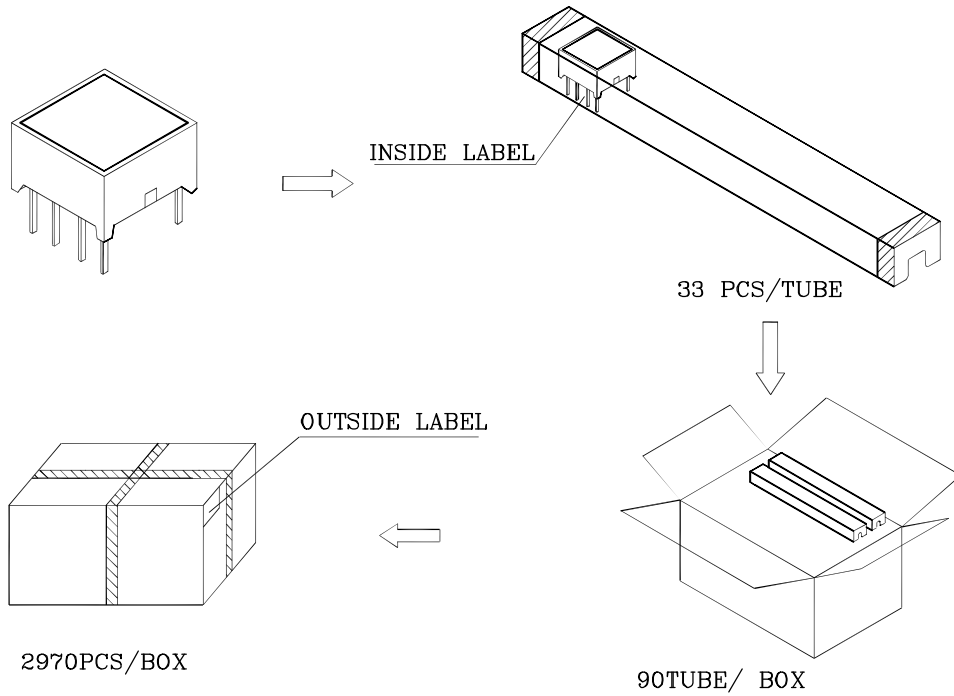
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

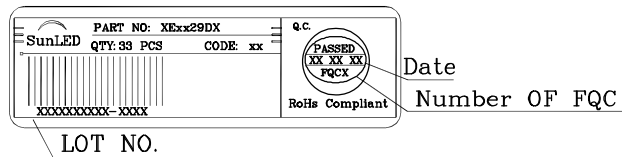
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

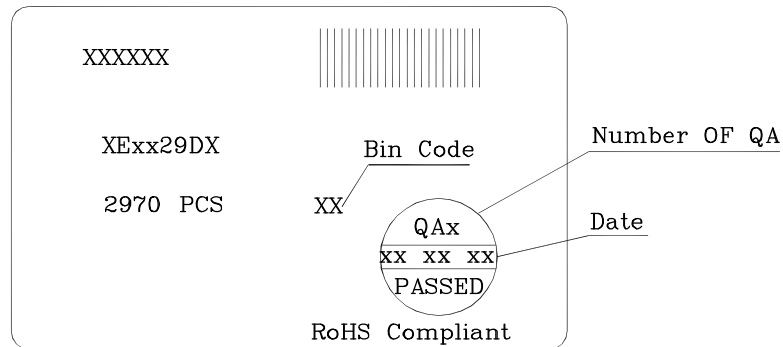
PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box



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